

Finland-Espoo: Miscellaneous general and special-purpose machinery

OJ S 97/2023 22/05/2023

Contract notice

Supplies

Legal Basis:

Directive 2014/24/EU

Section I: Contracting authority

I.1. Name and addresses

Official name: VTT Technical Research Centre of Finland Ltd

National registration number: 2647375-4

Postal address: P.O. Box 1000, VTT

Town: Espoo

NUTS code: FI1 Manner-Suomi

Postal code: 02044

Country: Finland

E-mail: kilpailutus@vtt.fi

Telephone: +358 20722111

Internet address(es):Main address: <https://www.vttresearch.com/en>**I.3. Communication**

The procurement documents are available for unrestricted and full direct access, free of charge, at: <https://tarjouspalvelu.fi/vtt?id=457497&tpk=1fdab13f-b9e8-4f11-9706-13824351e901>

Additional information can be obtained from the abovementioned address

Tenders or requests to participate must be submitted to the abovementioned address

I.4. Type of the contracting authority

Body governed by public law

I.5. Main activity

Other activity: Research and development

Section II: Object

II.1. Scope of the procurement**II.1.1. Title**

Si & Silicon oxide CMP

Reference number: Reg. no 32/206/2023

II.1.2. Main CPV code

42900000 Miscellaneous general and special-purpose machinery

II.1.3. Type of contract

Supplies

II.1.4. Short description

The object of the tender is an Automatic Chemical Mechanical Polisher (later also "Equipment"), for the polishing of typical films and substrates like Si, Si-compounds, Ge and other typical wafers used in semiconductor industry of 100, 150 and 200mm diameter. The equipment shall be designed with at least two polishing platens with integrated in-situ capable pad conditioning systems, an end-point detection on at least one platen, multi-zone carrier heads for all wafer diameters and a slurry feed system for at least 3 slurries. In addition, a supporting wafer cleaning system either integrated or stand-alone is an optional part of the tendering procedure.

The object of the tender process is described in more detail in the invitation to tender documents.

II.1.5. Estimated total value

Value excluding VAT: 800 000,00 EUR

II.1.6. Information about lots

This contract is divided into lots: no

II.2. Description

II.2.3. Place of performance

NUTS code: FI1B Helsinki-Uusimaa

II.2.4. Description of the procurement

The object of the tender is an Automatic Chemical Mechanical Polisher (later also "Equipment"), for the polishing of typical films and substrates like Si, Si-compounds, Ge and other typical wafers used in semiconductor industry of 100, 150 and 200mm diameter. The equipment shall be designed with at least two polishing platens with integrated in-situ capable pad conditioning systems, an end-point detection on at least one platen, multi-zone carrier heads for all wafer diameters and a slurry feed system for at least 3 slurries. In addition, a supporting wafer cleaning system either integrated or stand-alone is an optional part of the tendering procedure.

The tool must comply with cleanroom equipment standard safety and contamination requirements.

The tool specs are based on the following factors:

- Polish finishing quality
- Wafer handling without errors and wafer loss
- End-point detection for layer clearing
- Achievable polishing rate profile

The pricing of the equipment will consist of the main price for the minimum tool requirements ("total price of the equipment") and a separate price for the optional parts, features and efforts.

The optional goods offered are not included in the total price of the equipment.

The object of the tender process is described in more detail in the invitation to tender documents.

II.2.5. Award criteria

Criteria below

Quality criterion - Name: Price / Weighting: 100

Price - Weighting: 100

II.2.6. Estimated value

II.2.7. Duration of the contract, framework agreement or dynamic purchasing system

Duration in months: 12

This contract is subject to renewal: no

II.2.10. Information about variants

Variants will be accepted: no

II.2.11. Information about options

Options: yes

Description of options:

The optional parts, features and efforts which are described in more detail in the invitation to tender documents:

- Handling of 4-inch wafers (equivalent to 100mm)
- Automatic clear wafer processing capability including wafer handling on CMP system
- Standalone or integrated post CMP cleaning system with two individual dual roller PVA brush units, megasonic option and spin dry, at least 1 chemical input, and for standalone additionally: automatic cassette to cassette capability for 6 and 8 wafers with clear wafer handling capability
- 100mm membrane carrier with multi-zone (at least 3) pressure system for material removal profile control with additional independent pressure control on retainer ring
- Maintenance set for 100mm wafer carrier including at least 2 retainer rings and 3 membranes
- Multi zone pad conditioning system, with pressure control for secondary platen
- Recommended set of maintenance parts needed for smooth operation for a period of two (2) years

Offering optional parts, features and efforts are not mandatory.

II.2.13. Information about European Union funds

The procurement is related to a project and/or programme financed by European Union funds: yes

Identification of the project: The procurement is related to project financed by EU funds (PREVAIL=Partnership for Realization and Validation of AI hardware Leadership).

II.2.14. Additional information

Additional information regarding the section II.2.7) above: Agreement shall enter into force on the latest date of signature by the Parties and shall be in force until the Equipment has been delivered and accepted, the user training has been held and agreed payment paid, excluding clauses which legal effects are meant to survive the termination or expiration of the Agreement.

Section III: Legal, economic, financial and technical information

III.1. Conditions for participation

III.1.1. Suitability to pursue the professional activity, including requirements relating to enrolment on professional or trade registers

List and brief description of conditions:

As stated in the invitation to tender documents.

III.1.2. Economic and financial standing

List and brief description of selection criteria:

Selection criteria as stated in the invitation to tender documents

III.1.3. Technical and professional ability

List and brief description of selection criteria:

Selection criteria as stated in the invitation to tender documents

III.2. Conditions related to the contract

III.2.2. Contract performance conditions

As stated in the invitation to tender documents.

Section IV: Procedure

IV.1. Description

IV.1.1. Type of procedure

Open procedure

IV.1.3. Information about a framework agreement or a dynamic purchasing system

IV.1.8. Information about the Government Procurement Agreement (GPA)

The procurement is covered by the Government Procurement Agreement: yes

IV.2. Administrative information

IV.2.2. Time limit for receipt of tenders or requests to participate

Date: 19/06/2023 Local time: 09:00

IV.2.3. Estimated date of dispatch of invitations to tender or to participate to selected candidates

IV.2.4. Languages in which tenders or requests to participate may be submitted

English

IV.2.6. Minimum time frame during which the tenderer must maintain the tender

Duration in months: 6 (from the date stated for receipt of tender)

IV.2.7. Conditions for opening of tenders

Date: 19/06/2023 Local time: 09:10

Place:

Espoo, Finland

Information about authorised persons and opening procedure: The given date is preliminary. VTT reserves the right to change the scheduled date and time. The opening of tenders shall not be a public event.

Section VI: Complementary information

VI.1. Information about recurrence

This is a recurrent procurement: no

VI.3. Additional information

This notice has links and/or attachments listed in <https://www.hankintailmoitukset.fi/en/public/procurement/88362/notice/128903>

VI.4. Procedures for review

VI.4.1. Review body

Official name: Markkinaoikeus

Postal address: Sörnäistenkatu 1

Town: Helsinki

Postal code: 00580

Country: Finland

E-mail: markkinaoikeus@oikeus.fi

Telephone: +358 295643300

Internet address: <http://www.oikeus.fi/markkinaoikeus>

VI.5. Date of dispatch of this notice

17/05/2023